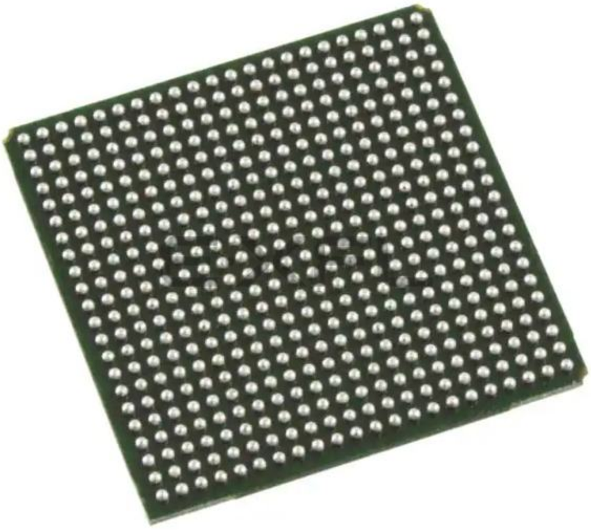
Lattice Semiconductor Corporation - LFE2-12SE-5FN484I Datasheet



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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

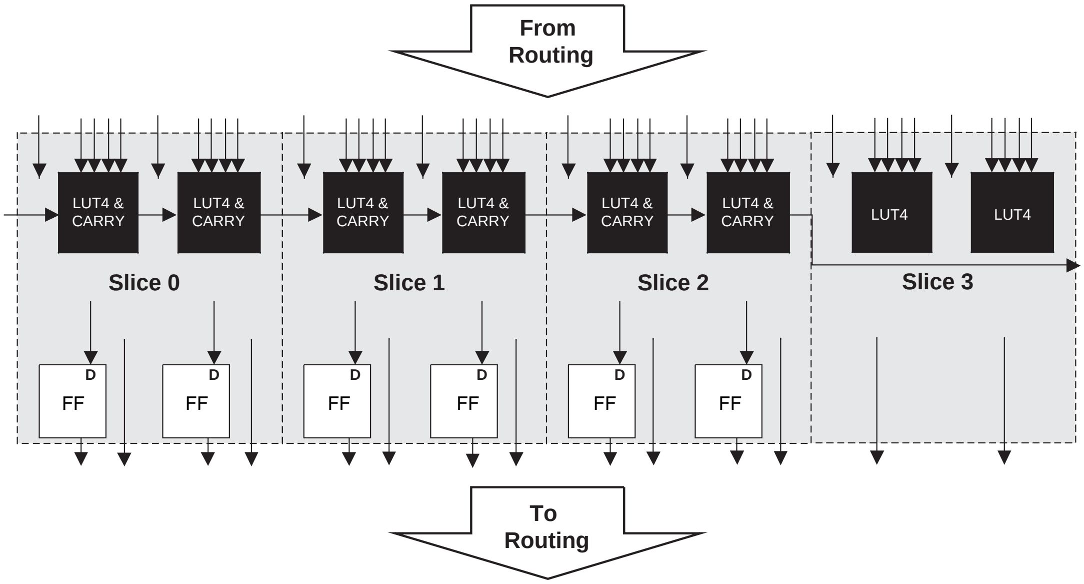
Details	
Product Status	Active
Number of LABs/CLBs	1500
Number of Logic Elements/Cells	12000
Total RAM Bits	226304
Number of I/O	297
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2-12se-5fn484i

PFU Blocks

The core of the LatticeECP2/M device consists of PFU blocks, which are provided in two forms, the PFU and PFF. The PFUs can be programmed to perform Logic, Arithmetic, Distributed RAM and Distributed ROM functions. PFF blocks can be programmed to perform Logic, Arithmetic and ROM functions. Except where necessary, the remainder of this data sheet will use the term PFU to refer to both PFU and PFF blocks.

Each PFU block consists of four interconnected slices, numbered 0-3 as shown in Figure 2-3. All the interconnections to and from PFU blocks are from routing. There are 50 inputs and 23 outputs associated with each PFU block.

Figure 2-3. PFU Diagram



Slice

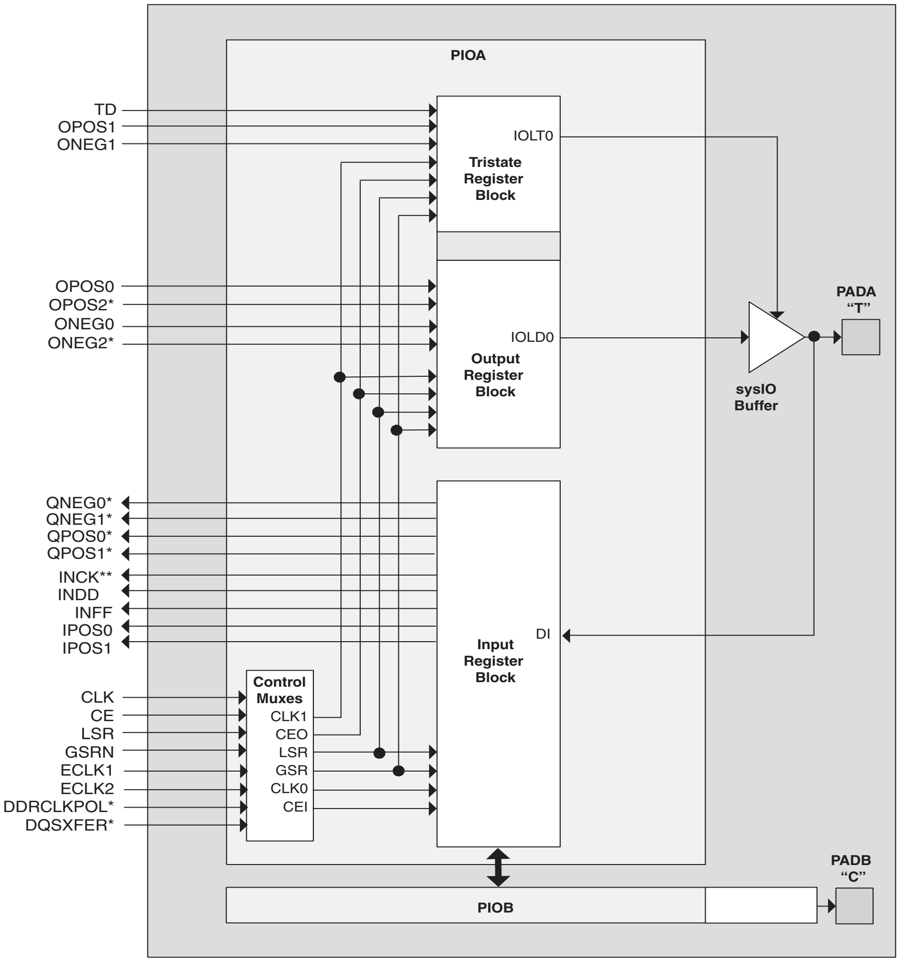
Slice 0 through Slice 2 contain two LUT4s feeding two registers, whereas Slice 3 contains two LUT4s only. For PFUs, Slice 0 and Slice 2 can also be configured as distributed memory, a capability not available in the PFF. Table 2-1 shows the capability of the slices in both PFF and PFU blocks along with the operation modes they enable. In addition, each PFU contains some logic that allows the LUTs to be combined to perform functions such as LUT5, LUT6, LUT7 and LUT8. There is control logic to perform set/reset functions (programmable as synchronous/asynchronous), clock select, chip-select and wider RAM/ROM functions. Figure 2-4 shows an overview of the internal logic of the slice. The registers in the slice can be configured for positive/negative and edge triggered or level sensitive clocks.

Table 2-1. Resources and Modes Available per Slice

	PFU BLock		PFF Block	
Slice	**Resources**	**Modes**	**Resources**	**Modes**
Slice 0	2 LUT4s and 2 Registers	Logic, Ripple, RAM, ROM	2 LUT4s and 2 Registers	Logic, Ripple, ROM
Slice 1	2 LUT4s and 2 Registers	Logic, Ripple, ROM	2 LUT4s and 2 Registers	Logic, Ripple, ROM
Slice 2	2 LUT4s and 2 Registers	Logic, Ripple, RAM, ROM	2 LUT4s and 2 Registers	Logic, Ripple, ROM
Slice 3	2 LUT4s	Logic, ROM	2 LUT4s	Logic, ROM

Slices 0, 1 and 2 have 14 input signals: 13 signals from routing and one from the carry-chain (from the adjacent slice or PFU). There are seven outputs: six to routing and one to carry-chain (to the adjacent PFU). Slice 3 has 13 input signals from routing and four signals to routing. Table 2-2 lists the signals associated with Slice 0 to Slice 2.

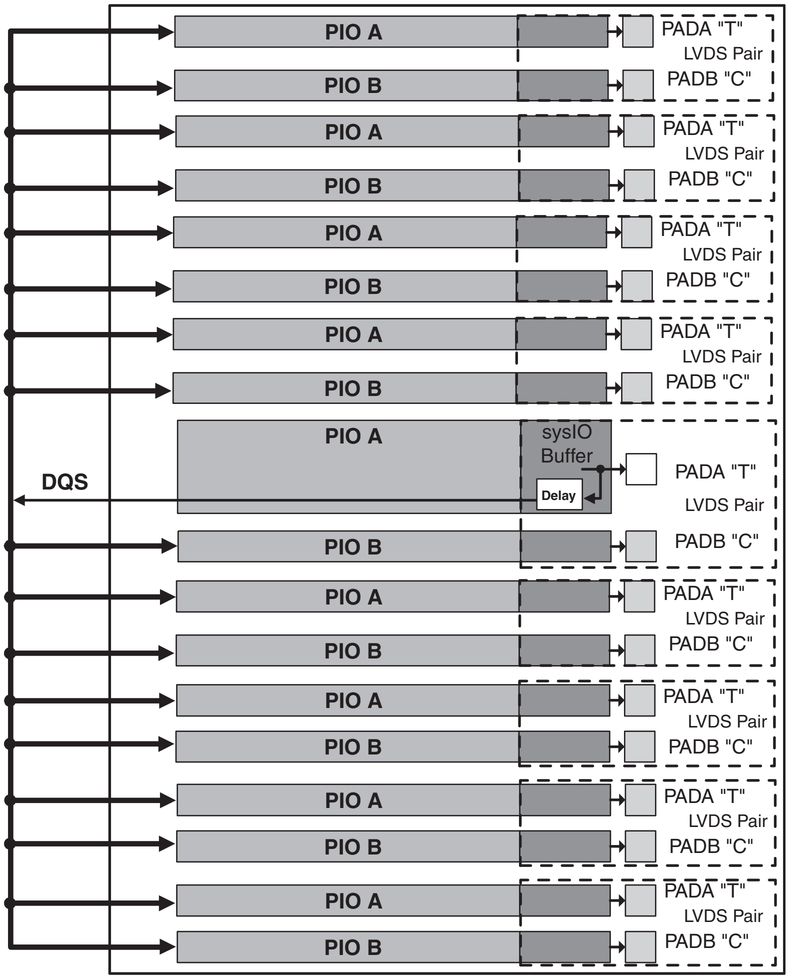
Figure 2-28. PIC Diagram



*Signals are available on left/right/bottom edges only.
** Selected blocks.

Two adjacent PIOs can be joined to provide a differential I/O pair (labeled as "T" and "C") as shown in Figure 2-28. The PAD Labels "T" and "C" distinguish the two PIOs. Approximately 50% of the PIO pairs on the left and right edges of the device can be configured as true LVDS outputs. All I/O pairs can operate as inputs.

Figure 2-34. DQS Input Routing for the Bottom Edge of the Device



DLL Calibrated DQS Delay Block

Source synchronous interfaces generally require the input clock to be adjusted in order to correctly capture data at the input register. For most interfaces a PLL is used for this adjustment. However, in DDR memories the clock (referred to as DQS) is not free-running so this approach cannot be used. The DQS Delay block provides the required clock alignment for DDR memory interfaces.

The DQS signal (selected PIOs only, as shown in Figure 2-35) feeds from the PAD through a DQS delay element to a dedicated DQS routing resource. The DQS signal also feeds polarity control logic, which controls the polarity of the clock to the sync registers in the input register blocks. Figure 2-35 and Figure 2-36 show how the DQS transition signals are routed to the PIOs.

The temperature, voltage and process variations of the DQS delay block are compensated by a set of calibration (6-bit bus) signals from two dedicated DLLs (DDR_DLL) on opposite sides of the device. Each DLL compensates DQS delays in its half of the device as shown in Figure 2-35. The DLL loop is compensated for temperature, voltage and process variations by the system clock and feedback loop.

SERDES Power Supply Requirements (LatticeECP2M Family Only)[1]

Over Recommended Operating Conditions

Symbol	Description	Typ.[2]	Units
Standby (Power Down)			
$I_{CCTX-SB}$	V_{CCTX} current (per channel)	10	µA
$I_{CCRX-SB}$	V_{CCRX} current (per channel)	75	µA
$I_{CCIB-SB}$	Input buffer current (per channel)	0	µA
$I_{CCOB-SB}$	Output buffer current (per channel)	0	µA
I_{CCP-SB}	SERDES PLL current (per quad)	30	µA
$I_{CCAX33-SB}$	SERDES termination current (per quad)	10	µA
Operating (Data Rate = 3.125 Gbps)			
$I_{CCTX-OP}$	V_{CCTX} current (per channel)	19	mA
$I_{CCRX-OP}$	V_{CCRX} current (per channel)	34	mA
$I_{CCIB-OP}$	Input buffer current (per channel)	4	mA
$I_{CCOB-OP}$	Output buffer current (per channel)	13	mA
I_{CCP-OP}	SERDES PLL current (per quad)	26	mA
$I_{CCAX33-OP}$	SERDES termination current (per quad)	0.01	mA

1. Equalization enabled, pre-emphasis disabled.
2. T_J = 25°C, power supplies at nominal voltage.

SERDES Power (LatticeECP2M Family Only)

Table 3-1 presents the SERDES power for one channel.

Table 3-1. SERDES Power[1]

Symbol	Description	Typ.[2]	Units
$P_{S-1CH-31}$	SERDES power (one channel @ 3.125 Gbps)	90	mW
$P_{S-1CH-25}$	SERDES power (one channel @ 2.5 Gbps)	87	mW
$P_{S-1CH-12}$	SERDES power (one channel @ 1.25 Gbps)	86	mW
$P_{S-1CH-02}$	SERDES power (one channel @ 250 Mbps)	76	mW

1. One quarter of the total quad power (includes contribution from common circuits, all channels in the quad operating, pre-emphasis disabled, equalization enabled).
2. Typical values measured at 25°C and 1.2V.

RSDS

The LatticeECP2/M devices support differential RSDS standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The RSDS input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-4 is one possible solution for RSDS standard implementation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

Figure 3-4. RSDS (Reduced Swing Differential Signaling)

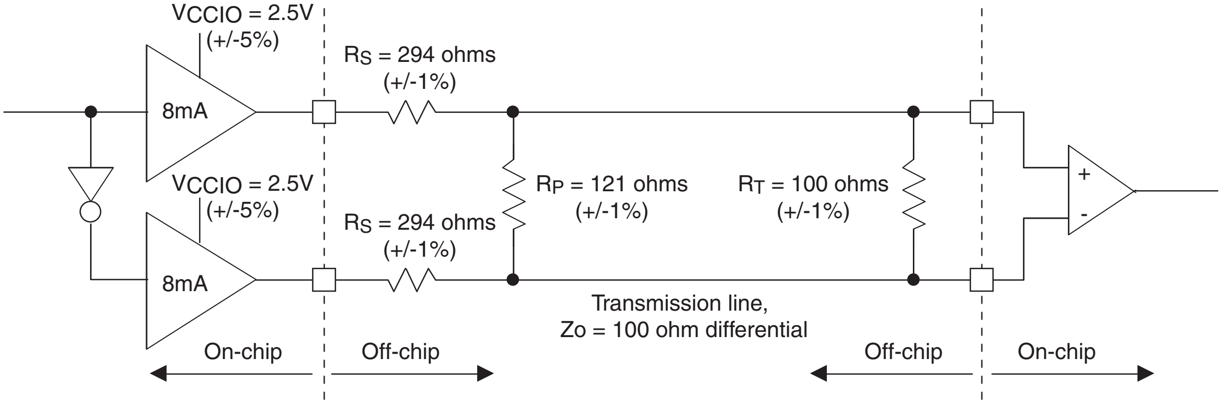


Table 3-5. RSDS DC Conditions[1]

Over Recommended Operating Conditions

Parameter	Description	Typical	Units
V_{CCIO}	Output Driver Supply (+/-5%)	2.50	V
Z_{OUT}	Driver Impedance	20	Ω
R_S	Driver Series Resistor (+/-1%)	294	Ω
R_P	Driver Parallel Resistor (+/-1%)	121	Ω
R_T	Receiver Termination (+/-1%)	100	Ω
V_{OH}	Output High Voltage	1.35	V
V_{OL}	Output Low Voltage	1.15	V
V_{OD}	Output Differential Voltage	0.20	V
V_{CM}	Output Common Mode Voltage	1.25	V
Z_{BACK}	Back Impedance	101.5	Ω
I_{DC}	DC Output Current	3.66	mA

1. For input buffer, see LVDS table.

LatticeECP2/M sysCONFIG Port Timing Specifications (Continued)

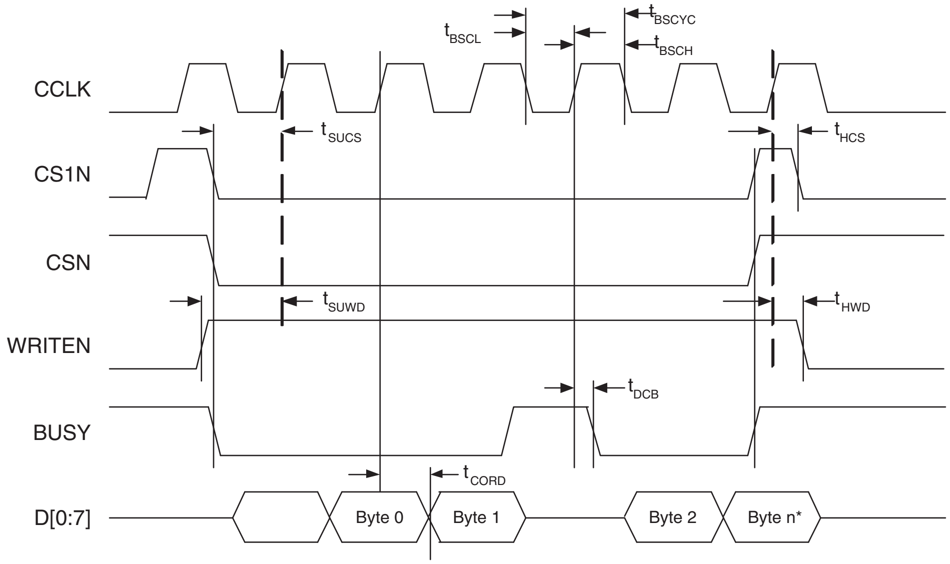
Over Recommended Operating Conditions

Parameter	Description	Min.	Max.	Units
f_{MAXSPI}	Max. CCLK Frequency - SPI Flash Read Opcode (0x03) (SPIFASTN = 1)	—	20	MHz
	Max. CCLK Frequency - SPI Flash Fast Read Opcode (0x0B) (SPIFASTN = 0)	—	50	MHz
	Max. CCLK Frequency - Encrypted Bitstream	—	10	MHz
t_{SUSPI}	SOSPI Data Setup Time Before CCLK	7	—	ns
t_{HSPI}	SOSPI Data Hold Time After CCLK	2	—	ns
t_{SUMCDI}	DI Setup to CCLK	7	—	ns
t_{HMCDI}	DI Hold from CCLK	1	—	ns

1. Re-toggling the PROGRAMN pin is not permitted until the INITN pin is high. Avoid consecutive toggling of the PROGRAMN.
2. For SED (Soft Error Detect), the SEDCLKIN operating frequency must be at least 20MHz. SEDCLKIN is derived from Master Clock Frequency that has a +/-30% variation..

Parameter	Min.	Max.	Units
Master Clock Frequency	Selected value - 30%	Selected value + 30%	MHz
Duty Cycle	40	60	%

Figure 3-14. sysCONFIG Parallel Port Read Cycle

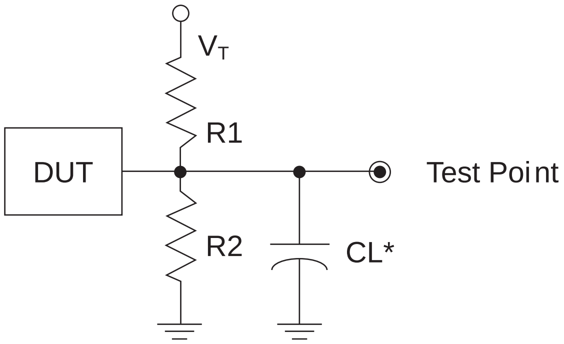


*n = last byte of read cycle.

Switching Test Conditions

Figure 3-22 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Table 3-19.

Figure 3-22. Output Test Load, LVTTL and LVCMOS Standards



*CL Includes Test Fixture and Probe Capacitance

Table 3-19. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	R_1	R_2	C_L	Timing Ref.	V_T
LVTTL and other LVCMOS settings (L -> H, H -> L)	∞	∞	0pF	LVCMOS 3.3 = 1.5V	—
				LVCMOS 2.5 = $V_{CCIO}/2$	—
				LVCMOS 1.8 = $V_{CCIO}/2$	—
				LVCMOS 1.5 = $V_{CCIO}/2$	—
				LVCMOS 1.2 = $V_{CCIO}/2$	—
LVCMOS 2.5 I/O (Z -> H)	∞	1MΩ		$V_{CCIO}/2$	—
LVCMOS 2.5 I/O (Z -> L)	1MΩ	∞		$V_{CCIO}/2$	V_{CCIO}
LVCMOS 2.5 I/O (H -> Z)	∞	100		V_{OH} - 0.10	—
LVCMOS 2.5 I/O (L -> Z)	100	∞		V_{OL} + 0.10	V_{CCIO}

Note: Output test conditions for all other interfaces are determined by the respective standards.

PICs and DDR Data (DQ) Pins Associated with the DDR Strobe (DQS) Pin

PICs Associated with DQS Strobe	PIO Within PIC	DDR Strobe (DQS) and Data (DQ) Pins
For Left and Right Edges of the Device		
P[Edge] [n-4]	A	DQ
	B	DQ
P[Edge] [n-3]	A	DQ
	B	DQ
P[Edge] [n-2]	A	DQ
	B	DQ
P[Edge] [n-1]	A	DQ
	B	DQ
P[Edge] [n]	A	[Edge]DQSn
	B	DQ
P[Edge] [n+1]	A	DQ
	B	DQ
P[Edge] [n+2]	A	DQ
	B	DQ
P[Edge] [n+3]	A	DQ
	B	DQ
For Bottom Edge of the Device		
P[Edge] [n-4]	A	DQ
	B	DQ
P[Edge] [n-3]	A	DQ
	B	DQ
P[Edge] [n-2]	A	DQ
	B	DQ
P[Edge] [n-1]	A	DQ
	B	DQ
P[Edge] [n]	A	[Edge]DQSn
	B	DQ
P[Edge] [n+1]	A	DQ
	B	DQ
P[Edge] [n+2]	A	DQ
	B	DQ
P[Edge] [n+3]	A	DQ
	B	DQ
P[Edge] [n+4]	A	DQ
	B	DQ

Notes:

1. “n” is a row PIC number.
2. The DDR interface is designed for memories that support one DQS strobe up to 15 bits of data for the left and right edges and up to 17 bits of data for the bottom edge. In some packages, all the potential DDR data (DQ) pins may not be available. PIC numbering definitions are provided in the “Signal Names” column of the Signal Descriptions table.

LatticeECP2 Pin Information Summary, LFE2-6 and LFE2-12

Pin Type		LFE2-6		LFE2-12			
		144 TQFP	256 fpBGA	144 TQFP	208 PQFP	256 fpBGA	484 fpBGA
Single Ended User I/O		90	190	93	131	193	297
Differential Pair User I/O		43	95	45	62	96	148
Configuration	TAP Pins	5	5	5	5	5	5
	Muxed Pins	14	14	14	14	14	14
	Dedicated Pins (Non TAP)	7	7	7	7	7	7
Non Configuration	Muxed Pins	34	54	33	40	54	57
	Dedicated Pins	3	3	3	3	3	3
VCC		10	7	10	14	7	16
VCCAUX		4	4	4	8	4	16
VCCPLL		0	0	0	0	0	0
VCCIO	Bank0	1	2	1	2	2	4
	Bank1	1	2	1	2	2	4
	Bank2	1	2	1	2	2	4
	Bank3	1	2	1	2	2	4
	Bank4	1	2	1	2	2	4
	Bank5	1	2	1	2	2	4
	Bank6	1	2	1	2	2	4
	Bank7	1	2	1	2	2	4
	Bank8	1	1	1	2	1	2
GND, GND0 to GND7		12	20	12	22	20	60
NC		4	3	1	0	0	44
Single Ended/ Differential I/O Pairs per Bank (including emulated with resistors)	Bank0	8/4	18/6	8/4	18/9	18/9	50/25
	Bank1	17/8	34/17	18/9	18/9	34/17	46/23
	Bank2	4/2	20/10	4/2	11/5	20/10	24/12
	Bank3	8/4	12/6	8/4	11/5	12/6	16/8
	Bank4	18/9	32/16	18/9	19/9	32/16	46/23
	Bank5	8/4	14/7	10/5	18/9	17/8	46/23
	Bank6	9/4	26/13	9/4	18/8	26/13	32/16
	Bank7	12/6	20/10	12/6	12/6	20/10	23/11
	Bank8	6/2	14/7	6/2	6/2	14/7	14/7
True LVDS I/O Pairs per Bank	Bank0 (Top Edge)	0	0	0	0	0	0
	Bank1 (Top Edge)	0	0	0	0	0	0
	Bank2 (Right Edge)	1	5	1	4	5	6
	Bank3 (Right Edge)	3	3	3	3	3	4
	Bank4 (Bottom Edge)	0	0	0	0	0	0
	Bank5 (Bottom Edge)	0	0	0	0	0	0
	Bank6 (Left Edge)	2	7	2	6	7	8
	Bank7 (Left Edge)	5	5	5	5	5	5
	Bank8 (Right Edge)	0	0	0	0	0	0

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
A7	PT35B	0		C	PT44B	0		C
B7	PT35A	0		T	PT44A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
F12	PT34B	0		C	PT43B	0		C
D10	PT34A	0		T	PT43A	0		T
H11	PT33B	0		C	PT42B	0		C
G11	PT33A	0		T	PT42A	0		T
GND	GNDIO0	-			GNDIO0	-		
A6	PT32B	0		C	PT41B	0		C
B6	PT32A	0		T	PT41A	0		T
D8	PT31B	0		C	PT40B	0		C
C8	PT31A	0		T	PT40A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
F11	PT30B	0		C	PT39B	0		C
E10	PT30A	0		T	PT39A	0		T
E9	PT29B	0		C	PT38B	0		C
D9	PT29A	0		T	PT38A	0		T
G10	PT28B	0		C	PT37B	0		C
GND	GNDIO0	-			GNDIO0	-		
H10	PT28A	0		T	PT37A	0		T
A5	PT27B	0		C	PT36B	0		C
B5	PT27A	0		T	PT36A	0		T
C7	PT26B	0		C	PT35B	0		C
VCCIO	VCCIO0	0			VCCIO0	0		
D7	PT26A	0		T	PT35A	0		T
E8	PT25B	0		C	PT34B	0		C
F10	PT25A	0		T	PT34A	0		T
F8	PT24B	0		C	PT33B	0		C
H9	PT24A	0		T	PT33A	0		T
C5	PT23B	0		C	PT32B	0		C
GND	GNDIO0	-			GNDIO0	-		
D5	PT23A	0		T	PT32A	0		T
B4	PT22B	0			PT31B	0		
VCCIO	VCCIO0	0			VCCIO0	0		
GND	GNDIO0	-			GNDIO0	-		
VCCIO	VCCIO0	0			VCCIO0	0		
GND	GNDIO0	-			GNDIO0	-		
VCCIO	VCCIO0	0			VCCIO0	0		
C4	PT10B	0		C	PT10B	0		C
GND	GNDIO0	-			GNDIO0	-		
C3	PT10A	0		T	PT10A	0		T
A4	PT9B	0		C	PT9B	0		C
A3	PT9A	0		T	PT9A	0		T
B3	PT8B	0		C	PT8B	0		C
VCCIO	VCCIO0	0			VCCIO0	0		
B2	PT8A	0		T	PT8A	0		T

LFE2M20E/SE and LFE2M35E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M20E/SE					LFE2M35E/SE			
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
GNDIO	GNDIO0	-			GNDIO0	-		
F7	PT9B	0		C	PT9B	0		C
G7	PT9A	0		T	PT9A	0		T
C3	PT8B	0		C	PT8B	0		C
D4	PT8A	0		T	PT8A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
F6	PT7B	0		C	PT7B	0		C
E6	PT7A	0		T	PT7A	0		T
E5	PT6B	0		C	PT6B	0		C
D6	PT6A	0		T	PT6A	0		T
GNDIO	GNDIO0	-			GNDIO0	-		
D3	PT5B	0		C	PT5B	0		C
E3	PT5A	0		T	PT5A	0		T
D5	PT4B	0		C	PT4B	0		C
E4	PT4A	0		T	PT4A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
C2	PT3B	0		C	PT3B	0		C
B2	PT3A	0		T	PT3A	0		T
B1	PT2B	0		C	PT2B	0		C
C1	PT2A	0		T	PT2A	0		T
R8	VCCPLL	-			VCCPLL	-		
H15	VCCPLL	-			VCCPLL	-		
H8	VCCPLL	-			VCCPLL	-		
R15	VCCPLL	-			VCCPLL	-		
J10	VCC	-			VCC	-		
J11	VCC	-			VCC	-		
J12	VCC	-			VCC	-		
J13	VCC	-			VCC	-		
K14	VCC	-			VCC	-		
K9	VCC	-			VCC	-		
L14	VCC	-			VCC	-		
L9	VCC	-			VCC	-		
M14	VCC	-			VCC	-		
M9	VCC	-			VCC	-		
N14	VCC	-			VCC	-		
N9	VCC	-			VCC	-		
P10	VCC	-			VCC	-		
P11	VCC	-			VCC	-		
P12	VCC	-			VCC	-		
P13	VCC	-			VCC	-		
B5	VCCIO0	0			VCCIO0	0		
B9	VCCIO0	0			VCCIO0	0		
E7	VCCIO0	0			VCCIO0	0		
H9	VCCIO0	0			VCCIO0	0		
D13	VCCIO1	1			VCCIO1	1		
E16	VCCIO1	1			VCCIO1	1		
H14	VCCIO1	1			VCCIO1	1		
E21	VCCIO2	2			VCCIO2	2		

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
M19	PR50A	3	RDQ52	T (LVDS)*
M18	PR49B	3	RDQ52	C
VCCIO	VCCIO3	3		
L16	PR49A	3	RDQ52	T
L22	PR48B	3	RDQ52	C (LVDS)*
L21	PR48A	3	RDQ52	T (LVDS)*
GNDIO	GNDIO3	-		
K22	PR46B	3	RLM3_SPLLC_FB_A	C
VCCIO	VCCIO3	3		
K21	PR46A	3	RLM3_SPLLT_FB_A	T
L17	PR45B	3	RLM3_SPLLC_IN_A	C (LVDS)*
L18	PR45A	3	RLM3_SPLLT_IN_A	T (LVDS)*
GNDIO	GNDIO3	-		
L20	PR44B	3		C
L19	PR44A	3		T
K16	PR43B	3		C (LVDS)*
K17	PR43A	3		T (LVDS)*
VCCIO	VCCIO3	3		
J16	PR42B	3	VREF2_3	C
K18	PR42A	3	VREF1_3	T
J22	PR41B	3	PCLKC3_0	C (LVDS)*
J21	PR41A	3	PCLKT3_0	T (LVDS)*
H22	PR39B	2	PCLKC2_0/RDQ36	C
H21	PR39A	2	PCLKT2_0/RDQ36	T
GNDIO	GNDIO2	-		
J17	PR38B	2	RDQ36	C (LVDS)*
J18	PR38A	2	RDQ36	T (LVDS)*
J20	PR37B	2	RDQ36	C
J19	PR37A	2	RDQ36	T
VCCIO	VCCIO2	2		
H16	PR36B	2	RDQ36	C (LVDS)*
H17	PR36A	2	RDQS36	T (LVDS)*
G22	PR35B	2	RDQ36	C
GNDIO	GNDIO2	-		
G21	PR35A	2	RDQ36	T
H20	PR34B	2	RDQ36	C (LVDS)*
H19	PR34A	2	RDQ36	T (LVDS)*
G16	PR33B	2	RUM3_SPLLC_FB_A/RDQ36	C
VCCIO	VCCIO2	2		
H18	PR33A	2	RUM3_SPLLT_FB_A/RDQ36	T
F22	PR32B	2	RUM3_SPLLC_IN_A/RDQ36	C (LVDS)*
F21	PR32A	2	RUM3_SPLLT_IN_A/RDQ36	T (LVDS)*
G20	PR30B	2	RDQ27	C

LFE2M35E/SE and LFE2M50E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2M35E/SE					LFE2M50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
N23	PR37A	3	PCLKT3_0	T (LVDS)*	PR41A	3	PCLKT3_0	T*
N24	PR35B	2	PCLKC2_0/RDQ32	C	PR39B	2	PCLKC2_0/RDQ36	C
N25	PR35A	2	PCLKT2_0/RDQ32	T	PR39A	2	PCLKT2_0/RDQ36	T
GNDIO	GNDIO2	-			GNDIO2	-		
M22	PR34B	2	RDQ32	C (LVDS)*	PR38B	2	RDQ36	C*
M24	PR34A	2	RDQ32	T (LVDS)*	PR38A	2	RDQ36	T*
M23	PR33B	2	RDQ32	C	PR37B	2	RDQ36	C
N26	PR33A	2	RDQ32	T	PR37A	2	RDQ36	T
VCCIO	VCCIO2	2			VCCIO2	2		
L22	PR32B	2	RDQ32	C (LVDS)*	PR36B	2	RDQ36	C*
L24	PR32A	2	RDQS32	T (LVDS)*	PR36A	2	RDQS36	T*
L23	PR31B	2	RDQ32	C	PR35B	2	RDQ36	C
GNDIO	GNDIO2	-			GNDIO2	-		
M20	PR31A	2	RDQ32	T	PR35A	2	RDQ36	T
M26	PR30B	2	RDQ32	C (LVDS)*	PR34B	2	RDQ36	C*
L26	PR30A	2	RDQ32	T (LVDS)*	PR34A	2	RDQ36	T*
K22	PR29B	2	RUM1_SPLLC_FB_A/RDQ32	C	PR33B	2	RUM3_SPLLC_FB_A/RDQ36	C
VCCIO	VCCIO2	2			VCCIO2	2		
M19	PR29A	2	RUM1_SPLLT_FB_A/RDQ32	T	PR33A	2	RUM3_SPLLT_FB_A/RDQ36	T
K25	PR28B	2	RUM1_SPLLC_IN_A/RDQ32	C (LVDS)*	PR32B	2	RUM3_SPLLC_IN_A/RDQ36	C*
K26	PR28A	2	RUM1_SPLLT_IN_A/RDQ32	T (LVDS)*	PR32A	2	RUM3_SPLLT_IN_A/RDQ36	T*
K24	PR26B	2	RDQ23	C	PR30B	2	RDQ27	C
K23	PR26A	2	RDQ23	T	PR30A	2	RDQ27	T
GNDIO	GNDIO2	-			GNDIO2	-		
L19	PR25B	2	RDQ23	C (LVDS)*	PR29B	2	RDQ27	C*
K21	PR25A	2	RDQ23	T (LVDS)*	PR29A	2	RDQ27	T*
J23	PR24B	2	RDQ23	C	PR28B	2	RDQ27	C
J24	PR24A	2	RDQ23	T	PR28A	2	RDQ27	T
VCCIO	VCCIO2	2			VCCIO2	2		
K20	PR23B	2	RDQ23	C (LVDS)*	PR27B	2	RDQ27	C*
J21	PR23A	2	RDQS23	T (LVDS)*	PR27A	2	RDQS27	T*
H21	PR22B	2	RDQ23	C	PR26B	2	RDQ27	C
GNDIO	GNDIO2	-			GNDIO2	-		
K18	PR22A	2	RDQ23	T	PR26A	2	RDQ27	T
H22	PR21B	2	RDQ23	C (LVDS)*	PR25B	2	RDQ27	C*
J20	PR21A	2	RDQ23	T (LVDS)*	PR25A	2	RDQ27	T*
J25	PR20B	2	RDQ23	C	PR24B	2	RDQ27	C
VCCIO	VCCIO2	2			VCCIO2	2		
J26	PR20A	2	RDQ23	T	PR24A	2	RDQ27	T
G21	PR19B	2	RDQ23	C (LVDS)*	PR23B	2	RDQ27	C*
J19	PR19A	2	RDQ23	T (LVDS)*	PR23A	2	RDQ27	T*
GNDIO	GNDIO2	-			GNDIO2	-		
H23	PR18B	2	RDQ15	C	PR21B	2		C
H24	PR18A	2	RDQ15	T	PR21A	2		T
H25	PR17B	2	RDQ15	C (LVDS)*	PR20B	2		C*
H26	PR17A	2	RDQ15	T (LVDS)*	PR20A	2		T*
VCCIO	VCCIO2	2			VCCIO2	2		
G22	PR16B	2	RDQ15	C	PR19B	2		C

LFE2M35E/SE and LFE2M50E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2M35E/SE					LFE2M50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
C15	URC_SQ_VCCIB2	12			URC_SQ_VCCIB2	12		
B15	URC_SQ_HDINN2	12		C	URC_SQ_HDINN2	12		C
C14	URC_SQ_VCCRX2	12			URC_SQ_VCCRX2	12		
A18	URC_SQ_HDOUTP2	12		T	URC_SQ_HDOUTP2	12		T
C18	URC_SQ_VCCOB2	12			URC_SQ_VCCOB2	12		
B18	URC_SQ_HDOUTN2	12		C	URC_SQ_HDOUTN2	12		C
C17	URC_SQ_VCCTX2	12			URC_SQ_VCCTX2	12		
B17	URC_SQ_HDOUTN3	12		C	URC_SQ_HDOUTN3	12		C
A16	URC_SQ_VCCOB3	12			URC_SQ_VCCOB3	12		
A17	URC_SQ_HDOUTP3	12		T	URC_SQ_HDOUTP3	12		T
C16	URC_SQ_VCCTX3	12			URC_SQ_VCCTX3	12		
B14	URC_SQ_HDINN3	12		C	URC_SQ_HDINN3	12		C
B13	URC_SQ_VCCIB3	12			URC_SQ_VCCIB3	12		
A14	URC_SQ_HDINP3	12		T	URC_SQ_HDINP3	12		T
C13	URC_SQ_VCCRX3	12			URC_SQ_VCCRX3	12		
-	-	-			GNDIO1	-		
-	-	-			VCCIO1	1		
E17	PT46B	1		C	PT55B	1		C
D17	PT46A	1		T	PT55A	1		T
GNDIO	GNDIO1	-			GNDIO1	-		
F17	PT45B	1		C	PT54B	1		C
D16	PT45A	1		T	PT54A	1		T
F19	PT44B	1		C	PT53B	1		C
F18	PT44A	1		T	PT53A	1		T
VCCIO	VCCIO1	1			VCCIO1	1		
E16	PT43B	1		C	PT52B	1		C
D15	PT43A	1		T	PT52A	1		T
G18	PT42B	1		C	PT51B	1		C
E15	PT42A	1		T	PT51A	1		T
GNDIO	GNDIO1	-			GNDIO1	-		
G17	PT41B	1		C	PT50B	1		C
E14	PT41A	1		T	PT50A	1		T
D14	PT40B	1		C	PT49B	1		C
D13	PT40A	1		T	PT49A	1		T
VCCIO	VCCIO1	1			VCCIO1	1		
F15	PT39B	1	VREF2_1	C	PT48B	1	VREF2_1	C
E12	PT39A	1	VREF1_1	T	PT48A	1	VREF1_1	T
H17	PT38B	1	PCLKC1_0	C	PT47B	1	PCLKC1_0	C
E13	PT38A	1	PCLKT1_0	T	PT47A	1	PCLKT1_0	T
C12	PT37B	0	PCLKC0_0	C	PT46B	0	PCLKC0_0	C
GNDIO	GNDIO0	-			GNDIO0	-		
G15	PT37A	0	PCLKT0_0	T	PT46A	0	PCLKT0_0	T
C11	PT36B	0	VREF2_0	C	PT45B	0	VREF2_0	C
F14	PT36A	0	VREF1_0	T	PT45A	0	VREF1_0	T

LFE2M35E/SE and LFE2M50E/SE Logic Signal Connections: 672 fpBGA (Cont.)

	LFE2M35E/SE				LFE2M50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
D23	NC	-			NC	-		
D24	NC	-			NC	-		
D25	NC	-			NC	-		
D26	NC	-			NC	-		
E20	NC	-			NC	-		
E21	NC	-			NC	-		
E25	NC	-			NC	-		
E26	NC	-			NC	-		
F20	NC	-			NC	-		
G20	NC	-			NC	-		
K10	NC	-			NC	-		
K17	NC	-			NC	-		
R4	NC	-			NC	-		
U10	NC	-			NC	-		
U23	NC	-			NC	-		
V10	NC	-			NC	-		
W7	NC	-			NC	-		
AB21	PB69B	4	BDQ69	C	NC	-		
AC20	PB58A	4	BDQ60	T	NC	-		
AC21	PB63A	4	BDQ60	T	NC	-		
AC22	PB69A	4	BDQS69****	T	NC	-		
AC23	PB71A	4	BDQ69	T	NC	-		
AC25	PB71B	4	BDQ69	C	NC	-		
AD26	PB70B	4	BDQ69	C	NC	-		
W20	PB72B	4	BDQ69	C	NC	-		
H7	L_VCCPLL	-			L_VCCPLL	-		
K6	L_VCCPLL	-			L_VCCPLL	-		
P7	L_VCCPLL	-			L_VCCPLL	-		
R8	L_VCCPLL	-			L_VCCPLL	-		
V18	R_VCCPLL	-			R_VCCPLL	-		
P20	R_VCCPLL	-			R_VCCPLL	-		
J17	R_VCCPLL	-			R_VCCPLL	-		
G19	R_VCCPLL	-			R_VCCPLL	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.

** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

*** For density migration, board design must take into account that these sysCONFIG pins are dual function for the lower density devices (ECP2M20 and ECP2M35). They can be either sysCONFIG pins or general purpose I/Os. These pins are dedicated pins for the higher density devices (ECP2M50, ECP2M70 and ECP2M100).

****Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

	LFE2M50E/SE				LFE2M70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
K13	VCCIO0	0			VCCIO0	0		
D17	VCCIO1	1			VCCIO1	1		
E22	VCCIO1	1			VCCIO1	1		
E25	VCCIO1	1			VCCIO1	1		
F19	VCCIO1	1			VCCIO1	1		
K18	VCCIO1	1			VCCIO1	1		
K19	VCCIO1	1			VCCIO1	1		
F28	VCCIO2	2			VCCIO2	2		
J25	VCCIO2	2			VCCIO2	2		
K28	VCCIO2	2			VCCIO2	2		
M21	VCCIO2	2			VCCIO2	2		
M24	VCCIO2	2			VCCIO2	2		
N21	VCCIO2	2			VCCIO2	2		
N28	VCCIO2	2			VCCIO2	2		
P21	VCCIO2	2			VCCIO2	2		
R25	VCCIO2	2			VCCIO2	2		
AA28	VCCIO3	3			VCCIO3	3		
AB25	VCCIO3	3			VCCIO3	3		
AE28	VCCIO3	3			VCCIO3	3		
T25	VCCIO3	3			VCCIO3	3		
U21	VCCIO3	3			VCCIO3	3		
V21	VCCIO3	3			VCCIO3	3		
V28	VCCIO3	3			VCCIO3	3		
W21	VCCIO3	3			VCCIO3	3		
W24	VCCIO3	3			VCCIO3	3		
AA18	VCCIO4	4			VCCIO4	4		
AA19	VCCIO4	4			VCCIO4	4		
AE19	VCCIO4	4			VCCIO4	4		
AF22	VCCIO4	4			VCCIO4	4		
AG17	VCCIO4	4			VCCIO4	4		
AG25	VCCIO4	4			VCCIO4	4		
AA12	VCCIO5	5			VCCIO5	5		
AA13	VCCIO5	5			VCCIO5	5		
AE12	VCCIO5	5			VCCIO5	5		
AF9	VCCIO5	5			VCCIO5	5		
AG14	VCCIO5	5			VCCIO5	5		
AG6	VCCIO5	5			VCCIO5	5		
AA3	VCCIO6	6			VCCIO6	6		
AB6	VCCIO6	6			VCCIO6	6		
AE3	VCCIO6	6			VCCIO6	6		
T6	VCCIO6	6			VCCIO6	6		
U10	VCCIO6	6			VCCIO6	6		
V10	VCCIO6	6			VCCIO6	6		
V3	VCCIO6	6			VCCIO6	6		
W10	VCCIO6	6			VCCIO6	6		
W7	VCCIO6	6			VCCIO6	6		
F3	VCCIO7	7			VCCIO7	7		
J6	VCCIO7	7			VCCIO7	7		

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
AE27	GND	-		
AE4	GND	-		
AE9	GND	-		
AF14	GND	-		
AF17	GND	-		
AF25	GND	-		
AF6	GND	-		
AJ10	GND	-		
AJ21	GND	-		
AJ27	GND	-		
AJ4	GND	-		
AK1	GND	-		
AK13	GND	-		
AK18	GND	-		
AK24	GND	-		
AK30	GND	-		
AK7	GND	-		
B10	GND	-		
B21	GND	-		
B27	GND	-		
B4	GND	-		
D25	GND	-		
D6	GND	-		
E14	GND	-		
E17	GND	-		
F22	GND	-		
F27	GND	-		
F4	GND	-		
F9	GND	-		
G12	GND	-		
G19	GND	-		
J24	GND	-		
J7	GND	-		
K14	GND	-		
K15	GND	-		
K16	GND	-		
K17	GND	-		
K27	GND	-		
K4	GND	-		
L14	GND	-		
L15	GND	-		
L16	GND	-		
L17	GND	-		

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE					LFE2M100E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AN29	LRC_SQ_VCCRX2	13			LRC_SQ_VCCRX2	13		
AM28	LRC_SQ_HDINN2	13		C	LRC_SQ_HDINN2	13		C
AL27	LRC_SQ_VCCIB2	13			LRC_SQ_VCCIB2	13		
AM29	LRC_SQ_HDINP2	13		T	LRC_SQ_HDINP2	13		T
AL29	LRC_SQ_VCCP	13			LRC_SQ_VCCP	13		
AL30	LRC_SQ_REFCLKP	13		T	LRC_SQ_REFCLKP	13		T
AK30	LRC_SQ_REFCLKN	13		C	LRC_SQ_REFCLKN	13		C
AK29	LRC_SQ_VCCAUX33	13			LRC_SQ_VCCAUX33	13		
AM30	LRC_SQ_HDINP1	13		T	LRC_SQ_HDINP1	13		T
AL31	LRC_SQ_VCCIB1	13			LRC_SQ_VCCIB1	13		
AM31	LRC_SQ_HDINN1	13		C	LRC_SQ_HDINN1	13		C
AN30	LRC_SQ_VCCRX1	13			LRC_SQ_VCCRX1	13		
AP30	LRC_SQ_HDOUTP1	13		T	LRC_SQ_HDOUTP1	13		T
AL32	LRC_SQ_VCCOB1	13			LRC_SQ_VCCOB1	13		
AP31	LRC_SQ_HDOUTN1	13		C	LRC_SQ_HDOUTN1	13		C
AN31	LRC_SQ_VCCTX1	13			LRC_SQ_VCCTX1	13		
AP32	LRC_SQ_HDOUTN0	13		C	LRC_SQ_HDOUTN0	13		C
AM34	LRC_SQ_VCCOB0	13			LRC_SQ_VCCOB0	13		
AP33	LRC_SQ_HDOUTP0	13		T	LRC_SQ_HDOUTP0	13		T
AN32	LRC_SQ_VCCTX0	13			LRC_SQ_VCCTX0	13		
AM32	LRC_SQ_HDINN0	13		C	LRC_SQ_HDINN0	13		C
AN34	LRC_SQ_VCCIB0	13			LRC_SQ_VCCIB0	13		
AM33	LRC_SQ_HDINP0	13		T	LRC_SQ_HDINP0	13		T
AN33	LRC_SQ_VCCRX0	13			LRC_SQ_VCCRX0	13		
AH28	CFG2	8			CFG2	8		
AD24	CFG1	8			CFG1	8		
AJ29	CFG0	8			CFG0	8		
AF25	PROGRAMN	8			PROGRAMN	8		
AJ28	CCLK	8			CCLK	8		
AE25	INITN	8			INITN	8		
AK31	DONE	8			DONE	8		
GNDIO	GNDIO8	-			GNDIO8	-		
AE24	WRITEN***	8			WRITEN***	8		
AJ30	CS1N***	8			CS1N***	8		
AD25	CSN***	8			CSN***	8		
AG29	D0/SPIFASTN***	8			D0/SPIFASTN***	8		
VCCIO	VCCIO8	8			VCCIO8	8		
AG28	D1***	8			D1***	8		
AG30	D2***	8			D2***	8		
AH29	D3***	8			D3***	8		
GNDIO	GNDIO8	-			GNDIO8	-		
AF26	D4***	8			D4***	8		
AH30	D5***	8			D5***	8		
AE26	D6***	8			D6***	8		
AJ31	D7/SPID0***	8			D7/SPID0***	8		
VCCIO	VCCIO8	8			VCCIO8	8		
AG27	DI/CSSPI0N***	8			DI/CSSPI0N***	8		
AK32	DOUT/CSON/CSSPI1N***	8			DOUT/CSON/CSSPI1N***	8		
AK33	BUSY/SISPI***	8			BUSY/SISPI***	8		

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-20E-5Q208I	131	1.2V	-5	PQFP	208	IND	20
LFE2-20E-6Q208I	131	1.2V	-6	PQFP	208	IND	20
LFE2-20E-5F256I	193	1.2V	-5	fpBGA	256	IND	20
LFE2-20E-6F256I	193	1.2V	-6	fpBGA	256	IND	20
LFE2-20E-5F484I	331	1.2V	-5	fpBGA	484	IND	20
LFE2-20E-6F484I	331	1.2V	-6	fpBGA	484	IND	20
LFE2-20E-5F672I	402	1.2V	-5	fpBGA	672	IND	20
LFE2-20E-6F672I	402	1.2V	-6	fpBGA	672	IND	20

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-35E-5F484I	331	1.2V	-5	fpBGA	484	IND	35
LFE2-35E-6F484I	331	1.2V	-6	fpBGA	484	IND	35
LFE2-35E-5F672I	450	1.2V	-5	fpBGA	672	IND	35
LFE2-35E-6F672I	450	1.2V	-6	fpBGA	672	IND	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-50E-5F484I	339	1.2V	-5	fpBGA	484	IND	50
LFE2-50E-6F484I	339	1.2V	-6	fpBGA	484	IND	50
LFE2-50E-5F672I	500	1.2V	-5	fpBGA	672	IND	50
LFE2-50E-6F672I	500	1.2V	-6	fpBGA	672	IND	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-70E-5F672I	500	1.2V	-5	fpBGA	672	IND	70
LFE2-70E-6F672I	500	1.2V	-6	fpBGA	672	IND	70
LFE2-70E-5F900I	583	1.2V	-5	fpBGA	900	IND	70
LFE2-70E-6F900I	583	1.2V	-6	fpBGA	900	IND	70

Date	Version	Section	Change Summary
June 2013 (cont.)	04.0 (cont.)	DC and Switching Characteristics	sysCLOCK SPLL Timing table – Corrected signal names for t_{RST} parameter.
			LatticeECP2/M sysCONFIG Port Timing Specifications table – added t_{SUMCDI} and t_{HMCDI} parameters.
September 2013	04.1	Architecture	Updated Selectable Master Clock (CCLK) Frequencies during Configuration table.
		DC and Switching Characteristics	Added information on f_{MAXSPI} parameter in LatticeECP2/M sysCONFIG Port Timing Specifications table.